



### Product Description

My-T-Bond® 2520 (A&B) is a thermally conductive, room temperature curing 2K-Epoxy system. After curing, it cures to a tough polymer and develops good bonding strength. It is designed to bond various electrical and electronic assemblies to dissipate heat efficiently.

### Applications:

- ❖ Used in electronic assemblies for encapsulating PCB and devices requiring high thermal dissipation.
- ❖ Used for permanent bonding of electronic devices for higher thermal dissipation.

### Properties

Technology	: Epoxy
Components	: 2K
Mix ratio by weight	: 1 : 1
Part A: Part B	
Appearance (mix)	: Blue
Viscosity (mix)	: 280000±15000cP
Specific Gravity, At 25±2 °C	
Part A	: 2.2±0.02
Part B	: 2.1±0.02
Thermal Conductivity	: 2 W/m <sup>2</sup> K
Dielectric Breakdown	: ≥10 KV/mm
Voltage ASTM D195	
Applications	: Bonding and Encapsulation

### Cure Properties

Pot Life at 25±2°C	: 30 - 45 minutes (100gm)
Total Cure at 25±2°C	: 24 Hours

### Adhesive Properties of Cured Material

**Lap Shear Strength**, ASTM D1002; After 24 hrs.

MS - MS	: ≥ 3 N/mm <sup>2</sup>
AL - AL	: ≥ 6 N/mm <sup>2</sup>

**Tensile Strength**, ASTM D897; After 24 hrs.

MS - MS	: ≥ 3 N/mm <sup>2</sup>
AL - AL	: ≥ 5 N/mm <sup>2</sup>

**Hardness**, ASTM D2240 After 24 hrs.

Durometer Shore D	: 55±5
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### Directions for Use

- ❖ For best performance, clean substrates to remove dust, grease, oil etc.

### For Hand use:

- ❖ To use, weighed separately epoxy resin (Part A) & Hardener (Part B) as per the specified quantity in the mixing ratio & mix to uniform consistency & apply.
- ❖ Mix small quantity at a time, so that the mixed material is consumed within a work life time.
- ❖ Higher temperature and large quantity will shorten work life time.

### Working

- ❖ Working time and cure time depends on temperature and mass.
- ❖ The higher the temperature, the faster the cure.
- ❖ The larger the mass of the material mixed, the faster the cure.
- ❖ To speed the cure of epoxies at low temperatures:
  - Store epoxy at room temperature.
  - Pre-heat repair surface until warm to the touch.
- ❖ To slow the cure of epoxies at high temperatures:
  - Mix epoxy in small masses to prevent rapid curing.
  - Cool resin/hardener component(s).

### Pack Size

My-T-Bond® 2520 (A&B) in 1 kg and 5 kg packing containers.

### Storage and Handling

- ❖ Store product in a cool and dry location in unopened containers preferably at 20°C
- ❖ Keep away from moisture, direct sunlight & heat.
- ❖ My-T-Bond® 2520 (A&B) will exhibit a shelf life of 6 months from the date of manufacture when stored as mentioned above.
- ❖ To prevent contamination of unused product, do not return any material to its original container. For further specific information, contact our technical service center.

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**Note**

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